### Product Category: Notebooks and Tablet PCs

<table>
<thead>
<tr>
<th>Marketing Name / Model</th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>[List multiple models if applicable.]</td>
<td></td>
</tr>
<tr>
<td>HP ZBook 15 G3 Mobile Workstation</td>
<td></td>
</tr>
</tbody>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries battery and RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cords, Adapter</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#).
Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>screw driver</td>
<td>philips #1</td>
</tr>
<tr>
<td>screw driver</td>
<td>T8</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. remove D-door
2. remove smart card and HDD module
3. remove battery
4. remove SSD/WLAN module/WWAN module/LVDS brk
5. remove thermal module
6. remove fan
7. remove KB
8. release hinge screws and divide log up and LCD
9. divide log up assy(remove speaker)
10. divide log up assy(remove LED board)
11. divide log up assy(remove touch pad)
12. divide log up assy(remove finger printer)
13. divide log up assy(remove RTC battery)
14. divide log up assy(remove VGA cap)
15. divide log up assy(remove MB assy)
16. divide log up assy(remove Powerbtn/app btn)
17. divide MB assy(remove MXM board)
18. divide MB assy(remove Ram)
19. divide LCD assy (remove BEZEL)
20. divide LCD assy (remove Hinge R and L)
21. divide LCD assy (remove panel)
22. divide LCD assy (remove ANTENNA)
23. divide LCD assy (remove LVDS cable and Camera module)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Step1. Remove D-door.  
Step2. Remove smart card and HDD.
Step 3. Remove battery.

Step 4. Remove SSD/WLAN module/WLAN antenna/LVDS cable.

Step 5. Remove thermal module.

Step 6. Remove fan.

Step 7. Remove KB

Step 8. Release hinge screws and divide log up and LCD

PSG instructions for this template are available at EL-MF877-01
Step 9. Divide log up assy (remove speaker).

Step 10. Divide log up assy (remove LED board).

Step 11. Divide log up assy (remove touch pad).

Step 12. Divide log up assy (remove finger printer).

Step 13. Divide log up assy (remove RTC battery).

Step 14. Divide log up assy (remove VGA cap).

PSG instructions for this template are available at EL-MF877-01
Step15. Divide log up assy (remove MB assy).

Step16. Divide log up assy (remove Power btn/app btn).

Step17. Divide MB assy (remove MXM board).

Step18. Divide MB assy (remove Ram).

Step19. Divide LCD assy (remove BEZEL).

Step 21. Divide LCD assy (remove panel).

Step 22. Divide LCD assy (remove ANTENNA)

Step 23. Divide LCD assy (remove LVDS cable and Camera module)